

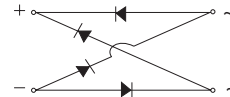
### Features

- Low forward voltage drop
- Glass passivated chip junction
- Ideal for automated placement
- Low profile space
- Low leakage current
- High forward surge capability
- High temperature soldering:  
260°C/10 seconds at terminals
- Component in accordance to  
RoHS 2011/65/EU and WEEE 2002/96/EC



RoHS  
COMPLIANT

MBF



### Mechanical Data

- **Case:**MBF  
Epoxy meets UL 94 V-0 flammability rating
- **Terminals:**Plated leads, solderable per  
MIL-STD-750, Method 2026
- **Polarity:** Polarity symbols marked on body

### Major Ratings and Characteristics

$I_{F(AV)}$	1.2A
$V_{RRM}$	50V to 1000V
$I_{FSM}$	35A
$I_R$	5 $\mu$ A
$V_F$	1.1V
$T_{Jmax.}$	150°C

### Maximum Ratings & Thermal Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Items	Symbol	MB 105F	MB 11F	MB 12F	MB 14F	MB 16F	MB 18F	MB 110F	Unit
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current @ $T_L=110^\circ\text{C}$	$I_{F(AV)}$	1.2							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	35							A
Thermal resistance from junction to ambient	$R_{\theta JA}^{(1)}$	85							
Thermal resistance from junction to lead	$R_{\theta JL}^{(1)}$	20							
Operating junction and storage temperature	$T_J, T_{STG}$	-55 to +150							°C

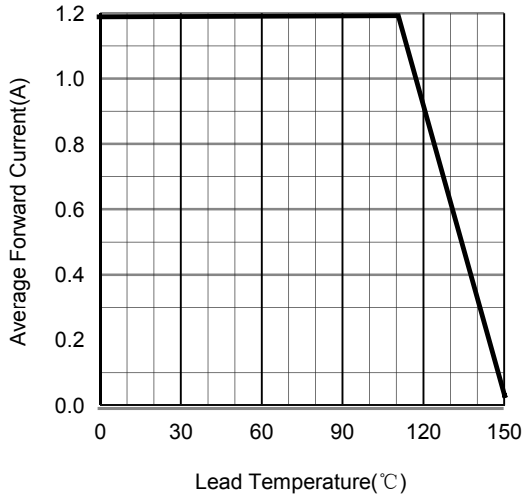
### Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Items	Test conditions	Symbol	Min	Typ	Max	Unit
Instantaneous forward voltage drop per leg	$I_F=1.0A$	$V_F$	-	-	1.1	V
Reverse current	$V_R=V_{DC}$	$I_R$	-	-	5	$\mu$ A
					100	
Typical junction capacitance per leg	$f=1.0\text{MHz}, V_R=4.0V$	$C_J$	-	13	-	pF

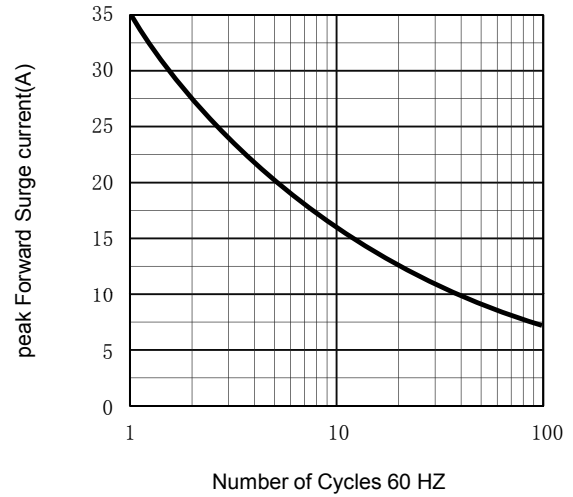
Notes:1. Units mounted on P.C.B with 0.05 x 0.05" (1.3 x 1.3 mm) pads

### Characteristic Curves ( $T_A=25\text{ }^\circ\text{C}$ unless otherwise noted)

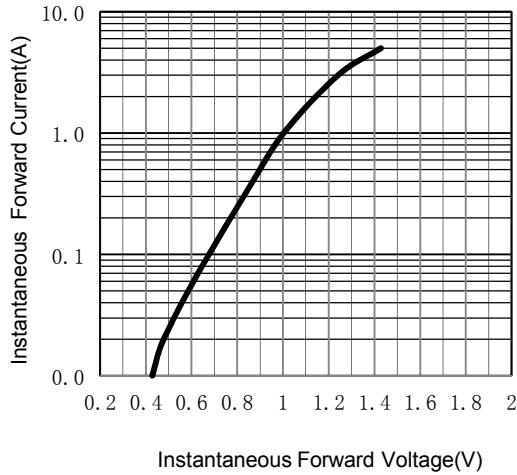
**Fig.1 Forward Current Derating Curve**



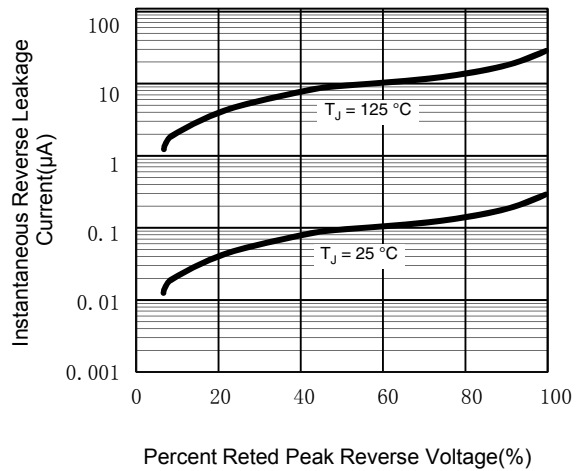
**Fig.2 Maximum Non-Repetitive Peak Forward Surge Current**



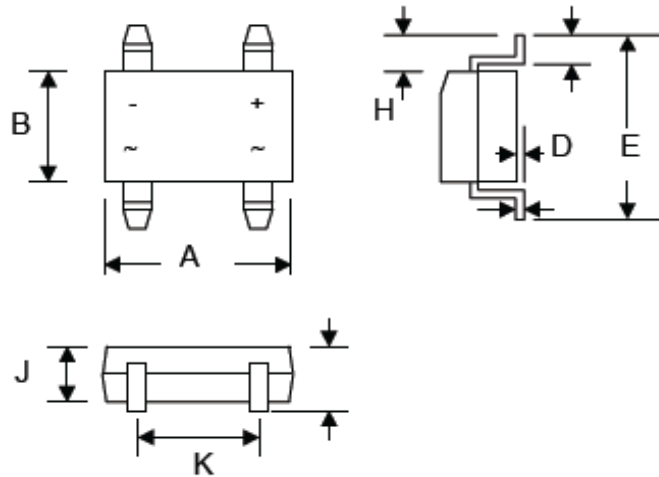
**Fig.3 Typical Instantaneous Forward Characteristics**



**Fig.4 Typical Reverse Leakage Characteristics**



### Package Outline



MBF

Dim	Min	Max
A	4.50	4.95
B	3.60	4.10
C	0.15	0.35
D	—	0.20
E	6.40	7.00
G	0.50	1.10
H	1.30	1.70
J	1.20	1.60
K	2.30	2.70
L	—	1.80
<b>All Dimensions in mm</b>		

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